

## Cure Schedule - Conductive Copper-Based

Mold Size Diameter	Heat Time (min)	Heat/Temp (°C/°F)	Cool Time (min)	Pressure (bar)	Mold Pressure (psi)
1" & 25 mm	5 - 6	150/300	3 - 4	4.0	4200
1.25" & 30 mm	7 - 8		4	4.5	3700
1.5" & 40 mm	8 - 9		4	5.0	3500
2" & 50 mm	8 - 9		5	6.0	3200

### Notes:

- All samples must be ultrasonically cleaned and then dried to remove any debris and/or grease.
- Mold release agent must be applied every time before a mounting cycle (200-10006 PTFE Spray is recommended).
- Duplex mounting requires 1-2 min longer heating time and 10 °C higher heating temperature.
- Cure cycle times and temperatures may vary for non-Allied presses. Please refer to the user's manual of your press for recommended cure cycles.